

DS25BR440

3.125 Gbps Quad LVDS Buffer with Transmit Pre-Emphasis and Receive Equalization

General Description

The DS25BR440 is a 3.125 Gbps Quad LVDS buffer optimized for high-speed signal routing and repeating over lossy FR-4 printed circuit board backplanes and balanced cables. Fully differential signal paths ensure exceptional signal integrity and noise immunity.

The DS25BR440 features two levels of transmit pre-emphasis (PE) and two levels of receive equalization (EQ). Both of these features compensate for interconnect losses and ultimately maximize noise margin. A loss-of-signal ($\overline{\text{LOS}}$) circuit monitors each input channel and a unique $\overline{\text{LOS}}$ pin is asserted when no signal is detected at that input

Wide input common mode range allows the switch to accept signals with LVDS, CML and LVPECL levels; the output levels are LVDS. A very small package footprint requires a minimal space on the board while the flow-through pinout allows easy board layout. Each differential input and output is internally terminated with a 100Ω resistor to lower device return losses, reduce component count and further minimize board space.

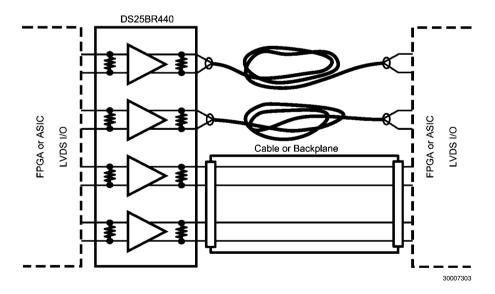
Features

- DC 3.125 Gbps low jitter, low skew, low power operation
- Pin selectable transmit pre-emphasis and receive equalization eliminate data dependant jitter
- Wide input common mode voltage range allows DCcoupled interface to LVDS, CML and LVPECL drivers
- LOS circuitry detects open inputs fault
- Integrated 100Ω input and output terminations
- 8 kV ESD on LVDS I/O pins protects adjoining components
- Small 6 mm x 6 mm LLP-40 space saving package

Applications

- Clock and data buffering and repeating
- Copper cable driving and equalization
- FR-4 equalization
- OC-48 / STM-16

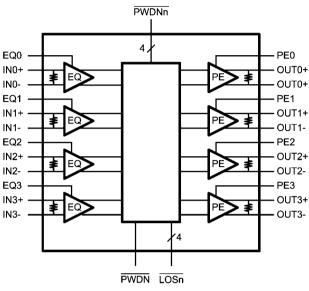
Typical Application



Ordering Code

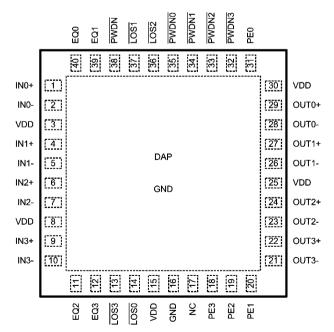
NSID	Function	Available Equalization Levels	Available Pre-Emphasis Levels
DS25BR440TSQ	Quad Buffer / Repeater	Off / On	Off / On

Block Diagram



30007301

Connection Diagram



DS25BR440 Pin Diagram

30007302

Pin Descriptions

Pin Name	Pin	I/O, Type	Pin Description
	Number		
IN0+, IN0- ,	1, 2,	I, LVDS	Inverting and non-inverting high speed LVDS input pins.
IN1+, IN1-,	4, 5,		
IN2+, IN2-,	6, 7,		
IN3+, IN3-	9, 10		
OUT0+, OUT0-,	29, 28,	O, LVDS	Inverting and non-inverting high speed LVDS output pins.
OUT1+, OUT1-,	27, 26,		
OUT2+, OUT2-,	24, 23,		
OUT3+, OUT3-	22, 21		
EQ0, EQ1,	40, 39,	I, LVCMOS	Receive equalization level select pins.
EQ2, EQ3	11, 12		
PE0, PE1,	31, 20,	I, LVCMOS	Transmit pre-emphasis level select pins.
PE2, PE3	19, 18		
PWDN0,	35,	I, LVCMOS	Channel output power down pins. When the PWDNn is set to L,
PWDN1,	34,		the channel output OUTn is in the power down mode. The LOS
PWDN2,	33,		circuitry on the corresponding input remains enabled.
PWDN3	32		
LOSO, LOS1,	14, 37,	O, LVCMOS	Loss Of Signal output pins, LOSn report when an open input fault
LOS2, LOS3	36, 13		condition is detected at the input, INn. These are open drain
			outputs. External pull up resistors are required.
NC	17	NC	NO CONNECT pins. May be left floating.
PWDN	38	I, LVCMOS	Device power down pin. When the PWDN is set to L, the device
		·	is in the power down mode. The LOS circuitry is disabled as well.
VDD	3, 8,	Power	Power supply pins.
	15,25, 30		
GND	16, DAP	Power	Ground pin and a pad (DAP - die attach pad).

Absolute Maximum Ratings (Note 4)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage -0.3V to +4V LVCMOS Input Voltage -0.3V to $(V_{CC} + 0.3V)$ LVCMOS Output Voltage -0.3V to $(V_{CC} + 0.3V)$ -0.3V to +4V LVDS Input Voltage LVDS Differential Input Voltage 0.0V to +1V LVDS Output Voltage -0.3V to $(V_{CC} + 0.3V)$ LVDS Differential Output Voltage 0.0V to +1V LVDS Output Short Circuit Current 5 ms Duration Junction Temperature +150°C Storage Temperature Range -65°C to +150°C Lead Temperature Range

Soldering (4 sec.) +260°C Maximum Package Power Dissipation at 25°C **SQA Package** 2.44W Derate SQA Package 19.49 mW/°C above +25°C

Package Thermal Resistance

CDM (Note 3)

 θ_{JA} θ_{IC} +3.8°C/W **ESD Susceptibility** HBM (Note 1) ≥8 kV MM (Note 2) ≥250V

+26.9°C/W

≥1250V

Note 1: Human Body Model, applicable std. JESD22-A114C Note 2: Machine Model, applicable std. JESD22-A115-A Note 3: Field Induced Charge Device Model, applicable std. JESD22-C101-C

Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage (V_{CC})	3.0	3.3	3.6	V
Receiver Differential Input Voltage (V _{ID})	0		1	V
Operating Free Air Temperature (T _A)	-40	+25	+85	°C

Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified. (Notes 5, 6, 7)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
LVCMOS	DC SPECIFICATIONS		-			
V _{IH}	High Level Input Voltage		2.0		V_{DD}	V
V _{IL}	Low Level Input Voltage		GND		0.8	V
I _{IH}	High Level Input Current	$V_{IN} = 3.6V$ $V_{CC} = 3.6V$		0	±10	μА
I _{IL}	Low Level Input Current	$V_{IN} = GND$ $V_{CC} = 3.6V$		0	±10	μА
V _{CL}	Input Clamp Voltage	$I_{CL} = -18 \text{ mA}, V_{CC} = 0V$		-0.9	-1.5	V
V _{OL}	Low Level Output Voltage	I _{OL} = 4 mA		0.26	0.4	V
LVDS IN	PUT DC SPECIFICATIONS					
V _{ID}	Input Differential Voltage		0		1	V
V _{TH}	Differential Input High Threshold	$V_{CM} = +0.05V \text{ or } V_{CC} -0.05V$		0	+100	mV
V _{TL}	Differential Input Low Threshold		-100	0		mV
V _{CMR}	Common Mode Voltage Range	V _{ID} = 100 mV	0.05		V _{CC} - 0.05	V
I _{IN}	Input Current	$V_{IN} = +3.6V \text{ or } 0V$ $V_{CC} = 3.6V \text{ or } 0V$		±1	±10	μА
C _{IN}	Input Capacitance	Any LVDS Input Pin to GND		1.7		pF
R _{IN}	Input Termination Resistor	Between IN+ and IN-		100	·	Ω

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
<u> </u>	UTPUT DC SPECIFICATIONS	Containent		. , , ,	l III dax	_ Cilito	
$\overline{V_{OD}}$	Differential Output Voltage		250	350	450	mV	
ΔV _{OD}	Change in Magnitude of V _{OD} for Complimentary Output States	$R_L = 100\Omega$	-35		35	mV	
V _{os}	Offset Voltage		1.05	1.2	1.375	V	
ΔV _{OS}	Change in Magnitude of V _{OS} for Complimentary Output States	$R_L = 100\Omega$	-35		35	mV	
I _{os}	Output Short Circuit Current (Note 8)	OUT to GND		-35	-55	mA	
		OUT to V _{CC}		7	55	mA	
C _{OUT}	Output Capacitance	Any LVDS Output Pin to GND		1.2		pF	
R _{OUT}	Output Termination Resistor	Between OUT+ and OUT-		100		Ω	
SUPPLY CURRENT							
I _{cc}	Supply Current	PE = OFF, EQ = OFF PWDN = H		162	190	mA	
I _{CCZ}	Power Down Supply Current	PWDN = L		55	63	mA	

Note 4: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions at which the device is functional and the device should not be operated beyond such conditions.

Note 5: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 6: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except V_{OD} and ΔV_{OD} .

Note 7: Typical values represent most likely parametric norms for $V_{CC} = +3.3V$ and $T_A = +25^{\circ}C$, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 8: Output short circuit current (I_{OS}) is specified as magnitude only, minus sign indicates direction only.

AC Electrical Characteristics (Notes 9, 10)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Cond	litions	Min	Тур	Max	Units
LVDS OUTPU	T AC SPECIFICATIONS						
t _{PLHD}	Differential Propagation Delay Low to High (Note 11)	D = 4000			390	600	ps
t _{PHLD}	Differential Propagation Delay High to Low (Note 11)	$-R_L = 100\Omega$			400	600	ps
t _{SKD1}	Pulse Skew It _{PLHD} – t _{PHLD} I (Notes 11, 12)				10	50	ps
t _{SKD2}	Channel to Channel Skew (Notes 11, 13)				18	65	ps
t _{SKD3}	Part to Part Skew (Notes 11, 14)				50	170	ps
t _{LHT}	Rise Time (Note 11)				80	160	ps
t _{HLT}	Fall Time (Note 11)	$R_L = 100\Omega$			80	160	ps
t _{ON}	Any PWDN to Output Active Time				8	20	μs
t _{OFF}	Any PWDN to Output Inactive Time				5	12	ns
	ORMANCE WITH EQ = Off, PE = Off (Note	11) (Figure 5)					
t _{RJ1}	Random Jitter (RMS Value)	V _{ID} = 350 mV	2.5 Gbps		0.5	1	ps
t _{RJ2}	No Test Channels (Note 15)	V _{CM} = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t _{DJ1}	Deterministic Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		6	22	ps
t _{DJ2}	No Test Channels (Note 16)	V _{CM} = 1.2V K28.5 (NRZ)	3.125 Gbps		10	29	ps
t _{TJ1}	Total Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		0.04	0.09	UI _{P-P}
t _{TJ2}	No Test Channels (Note 17)	V _{CM} = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.06	0.14	UI _{P-P}
JITTER PERF	ORMANCE WITH EQ = Off, PE = On (Note	· ' '					
t _{RJ1B}	Random Jitter (RMS Value)	V _{ID} = 350 mV	2.5 Gbps		0.5	1	ps
t _{RJ2B}	Test Channel B (Note 15)	V _{CM} = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t _{DJ1B}	Deterministic Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		7	15	ps
t _{DJ2B}	Test Channel B (Note 16)	V _{CM} = 1.2V K28.5 (NRZ)	3.125 Gbps		4	23	ps
t _{TJ1B}	Total Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		0.05	0.10	UI _{P-P}
t _{TJ2B}	Test Channel B (Note 17)	V _{CM} = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.06	0.14	UI _{P-P}
JITTER PERF	ORMANCE WITH EQ = On, PE = Off (Note	11) (Figures 7, 9)					
t _{RJ1D}	Random Jitter (RMS Value)	V _{ID} = 350 mV	2.5 Gbps		0.5	1	ps
t _{RJ2D}	Test Channel D (Note 15)	V _{CM} = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t _{DJ1D}	Deterministic Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		14	30	ps
t _{DJ2D}	Test Channel D (Note 16)	$V_{CM} = 1.2V$ K28.5 (NRZ)	3.125 Gbps		15	30	ps
t _{TJ1D}	Total Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		0.08	0.15	UI _{P-P}
t _{TJ2D}	Test Channel D (Note 17)	V _{CM} = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.10	0.17	UI _{P-P}

Symbol	Parameter	Conditions		Min	Тур	Max	Units
JITTER PERFORMANCE WITH EQ = On, PE = On (Note 11) (Figures 8, 9)							
t _{RJ1BD}	Random Jitter (RMS Value)	V _{ID} = 350 mV	2.5 Gbps		0.5	1	ps
t _{RJ2BD}	Input Test Channel D Output Test Channel B (Note 15)	V _{CM} = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t _{DJ1BD}	Deterministic Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		11	23	ps
t _{DJ2BD}	Input Test Channel D Output Test Channel B (Note 16)	V _{CM} = 1.2V K28.5 (NRZ)	3.125 Gbps		5	24	ps
t _{TJ1BD}	Total Jitter (Peak to Peak)	V _{ID} = 350 mV	2.5 Gbps		0.08	0.14	UI _{P-P}
t _{TJ2BD}	Input Test Channel D Output Test Channel B (Note 17)	V _{CM} = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.10	0.20	UI _{P-P}

Note 9: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 10: Typical values represent most likely parametric norms for $V_{CC} = +3.3V$ and $T_A = +25^{\circ}C$, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 11: Specification is guaranteed by characterization and is not tested in production.

Note 12: t_{SKD1} , $t_{PLHD} - t_{PHLD}$, Pulse Skew, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

Note 13: t_{SKD2}, Channel to Channel Skew, is the difference in propagation delay (t_{PLHD} or t_{PHLD}) among all output channels in Broadcast mode (any one input to all outputs).

Note 14: t_{SKD3}, Part to Part Skew, is defined as the difference between the minimum and maximum differential propagation delays. This specification applies to devices at the same V_{CC} and within 5°C of each other within the operating temperature range.

Note 15: Measured on a clock edge with a histogram and an acummulation of 1500 histogram hits. Input stimulus jitter is subtracted geometrically.

Note 16: Tested with a combination of the 1100000101 (K28.5+ character) and 0011111010 (K28.5- character) patterns. Input stimulus jitter is subtracted algebraically.

Note 17: Measured on an eye diagram with a histogram and an acummulation of 3500 histogram hits. Input stimulus jitter is subtracted.

DC Test Circuits

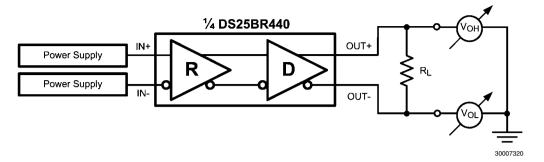


FIGURE 1. Differential Driver DC Test Circuit

AC Test Circuits and Timing Diagrams

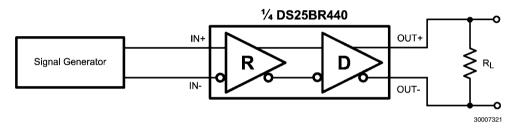


FIGURE 2. Differential Driver AC Test Circuit

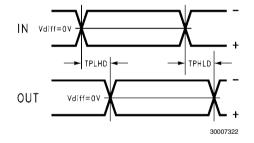


FIGURE 3. Propagation Delay Timing Diagram

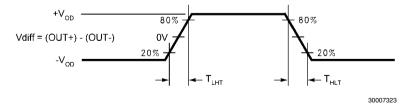


FIGURE 4. LVDS Output Transition Times

Pre-Emphasis and Equalization Test Circuits

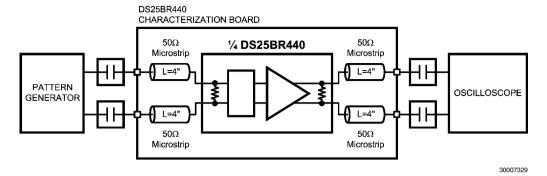


FIGURE 5. Jitter Performance Test Circuit

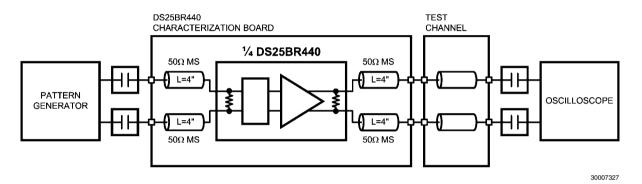


FIGURE 6. Pre-emphasis Performance Test Circuit

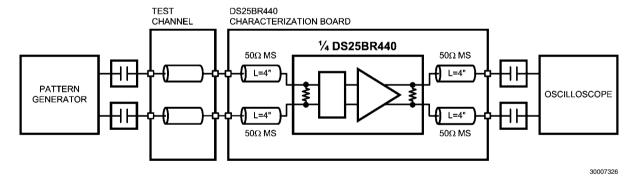


FIGURE 7. Equalization Performance Test Circuit

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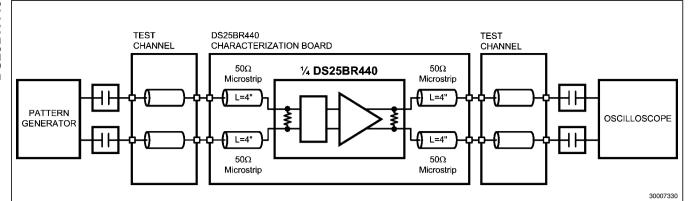


FIGURE 8. Pre-emphasis and Equalization Performance Test Circuit

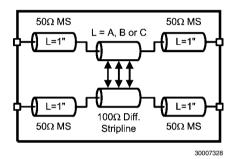


FIGURE 9. Test Channel Block Diagram

Test Channel Loss Characteristics

The test channel was fabricated with Polyclad PCL-FR-370-Laminate/PCL-FRP-370 Prepreg materials (Dielectric constant of 3.7 and Loss Tangent of 0.02). The edge coupled differential striplines have the following geometries: Trace Width (W) = 5 mils, Gap (S) = 5 mils, Height (B) = 16 mils.

Test Channel	Length		Insertion Loss (dB)				
	(inches)	500 MHz	750 MHz	1000 MHz	1250 MHz	1500 MHz	1560 MHz
А	10	-1.2	-1.7	-2.0	-2.4	-2.7	-2.8
В	20	-2.6	-3.5	-4.1	-4.8	-5.5	-5.6
С	30	-4.3	-5.7	-7.0	-8.2	-9.4	-9.7
D	15	-1.6	-2.2	-2.7	-3.2	-3.7	-3.8
E	30	-3.4	-4.5	-5.6	-6.6	-7.7	-7.9
F	60	-7.8	-10.3	-12.4	-14.5	-16.6	-17.0

Functional Description

The DS25BR440 is a 3.125 Gbps Quad LVDS buffer optimized for high-speed signal routing and repeating over lossy FR-4 printed circuit board backplanes and balanced cables. The DS25BR440 has a pre-emphasis control pin for each

OFF setting and an equalization control pin for each input for switching the receive equalization to ON and OFF setting. The following are the transmit pre-emphasis and receive equalization truth tables.

output for switching the transmit pre-emphasis to ON and Transmit Pre-emphasis Truth Table

OUTPUT OUTn, n = {0, 1, 2, 3}				
CONTROL Pin (PEn) State	Pre-emphasis Level			
0	OFF			
1	ON			

Transmit Pre-emphasis Level Selection for an Output OUTn

Receive Equalization Truth Table

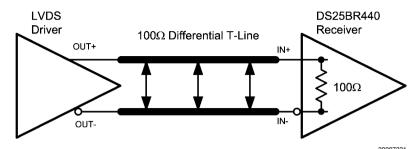
INPUT INn, n = {0, 1, 2, 3}				
CONTROL Pin (EQn) State	Equalization Level			
0	OFF			
1	ON			

Receive Equalization Level Selection for an Input INn

Input Interfacing

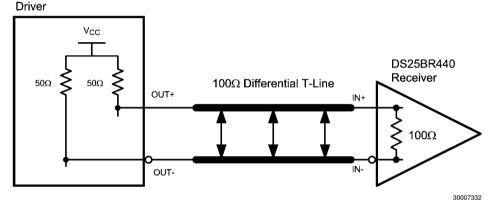
The DS25BR440 accepts differential signals and allows simple AC or DC coupling. With a wide common mode range, the DS25BR440 can be DC-coupled with all common differential

drivers (i.e. LVPECL, LVDS, CML). The following three figures illustrate typical DC-coupled interface to common differential drivers. Note that the DS25BR440 inputs are internally terminated with a 100Ω resistor.

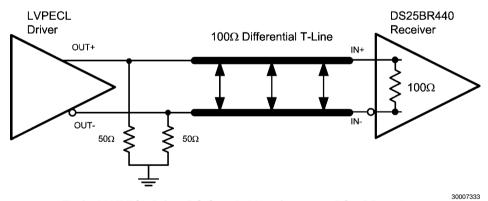


Typical LVDS Driver DC-Coupled Interface to an DS25BR440 Input

CML3.3V or CML2.5V



Typical CML Driver DC-Coupled Interface to an DS25BR440 Input

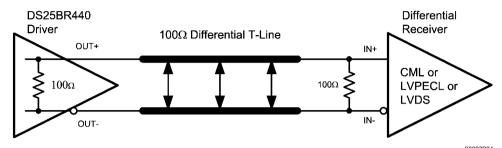


Typical LVPECL Driver DC-Coupled Interface to an DS25BR440 Input

Output Interfacing

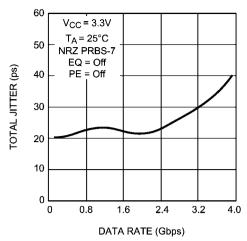
The DS25BR440 outputs signals compliant to the LVDS standard. Its outputs can be DC-coupled to most common differential receivers. The following figure illustrates typical DC-coupled interface to common differential receivers and

assumes that the receivers have high impedance inputs. While most differential receivers have a common mode input range that can accomodate LVDS compliant signals, it is recommended to check respective receiver's data sheet prior to implementing the suggested interface implementation.

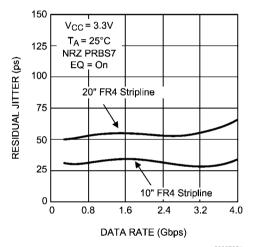


Typical DS25BR440 Output DC-Coupled Interface to an LVDS, CML or LVPECL Receiver

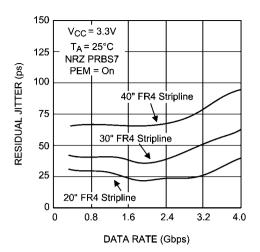
Typical Performance



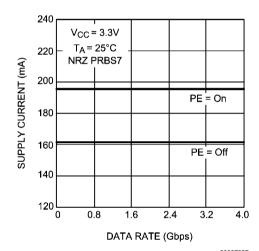
Total Jitter as a Function of Data Rate



Residual Jitter as a Function of Data Rate, FR4 Stripline Length and EQ Level

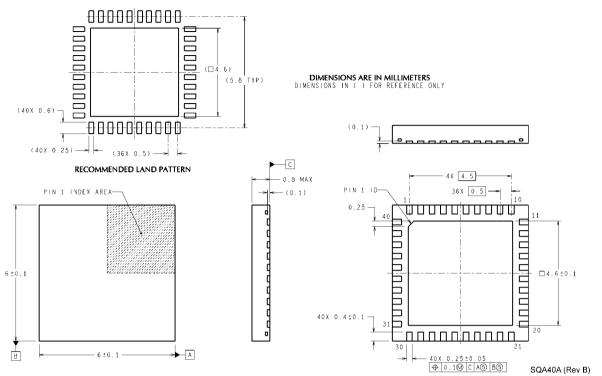


Residual Jitter as a Function of Data Rate, FR4 Stripline Length and PE Level



Supply Current as a Function of Data Rate and PE Level

Physical Dimensions inches (millimeters) unless otherwise noted



Order Number DS25BR440TSQ
NS Package Number SQA40A
(See AN-1187 for PCB Design and Assembly Recommendations)

Notes

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